

Electronic Patent Application Fee Transmittal

Application Number:	10612281
Filing Date:	30-Jun-2003
Title of Invention:	Bond finger on via substrate, process of making same, package made thereby, and method of assembling same
First Named Inventor:	Brian Taggart
Filer:	Joseph P. Mehrle/Anne Richards
Attorney Docket Number:	884.853US1

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Notice of appeal	1401	1	500	500
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500